| ABSOCIATION CONNECTING<br>ELECTRONCS INDUSTRIES®<br>INDUSTRIES®<br>INTERNATION CONNECTING | , Bannockb   | urn, Illinois. A                       | Il rights reserved untions. | under both       | This docum<br>level parts, t | ent is a declar<br>the declaration | ation of the ation | he substance<br>asses all low | s within the manufa<br>er level materials fo | cturer listed<br>or which the | d item. Note:<br>e manufacture  | if the item is an a<br>r has engineering | ssembly with lower responsibility. |  |
|---|--|--|-----------------------------|------------------|------------------------------|------------------------------------|--|-------------------------------|--|-------------------------------|---------------------------------|--|------------------------------------|--|
|   | IPC Web Site for Information on IPC-1752 Standard Form<br>http://www.ipc.org/IPC-175x Distri |  |                             |                  |                              |                                    |  |                               |  | aterials and                  | ials and Mfg Information        |  |                                    |  |
| Supplier Information  |  |  |                             |                  |                              |                                    |  |                               |  |                               |                                 |  |                                    |  |
| Company name*   | Company unique ID  |  |                             |                  | Unique ID Authority          |                                    |  |                               |  | Response Date*                |                                 |  |                                    |  |
| onsemi  |  |  |                             |                  |                              |                                    | 2023-0   |                               |  | 23-06-08                      |                                 |  |                                    |  |
| Contact Name Title - Con  |  |  | tle - Contact               |                  |                              | Phone - Contact*                   |  |                               |  | Email                         | Email - Contact*                |  |                                    |  |
| Product-Env-Stewards Produc   |  |  | Product Enviro Compliance   |                  |                              | NA                                 |  |                               |  | Prod                          | Product-Env-Stewards@onsemi.com |  |                                    |  |
| Authorized Representative* Title - Represe  |  |  | esentative                  |                  |                              | Phone - Representative*            |  |                               | Email  | Email - Representative*       |                                 |  |                                    |  |
| Product-Env-Stewards Pro  |  |  | Product Enviro Compliance   |                  |                              | NA                                 |  |                               |  | Prod                          | Product-Env-Stewards@onsemi.com |  |                                    |  |
| Requester Item Number   | Mfr Item   | Number Mfr Item Name                   |                             |                  |                              | Effective Da                       | te Vers  | sion                          | Manufacturing Site                           | e                             | Weight*                         | UOM                                      | Unit Type                          |  |
|   | NCP812   | NCP81234MNTXG Dual-Channel/Ty<br>DrMOS |                             | vo-Phase Control | ller for                     | 2023-06-08                         |  |                               | PH1  |                               | 55.47                           | mg                                       | Each                               |  |
| Manufacturing Proccess Informatio   | n  |  |                             |                  |                              |                                    |  |                               |  |                               |                                 |  |                                    |  |
| Terminal Plating / Grid Array Mate  | Terminal Plating / Grid Array Material Terminal Base All                                     |  | Alloy                       | J-STD-020 MSL    | Rating                       | Peak Pro                           | ocess Boo  | dy Temperat                   | ure Max Time at F                            | eak Tempe                     | rature Num                      | ber of Reflow Cy                         | cles                               |  |
| Matte Tin (Sn) - annealed CU Alloy  |  |  |                             | 1                |                              | 260                                |  | С                             | 30   | sec                           | onds 3                          |  |                                    |  |
| Comments  |  |  |                             |                  |                              |                                    |  |                               |  |                               |                                 |  |                                    |  |
| level 1 - maximum time at peak temperature  | during sol   | dering is 10-3                         | 0 seconds                   |                  |                              |                                    |  |                               |  |                               |                                 |  |                                    |  |
| For more information regarding material co  | mposition  | please refer to                        | page 3                      |                  |                              |                                    |  |                               |  |                               |                                 |  |                                    |  |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the   | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | ances per the definitio  | on above  | Supplier Acceptance                             | * Accepted  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le   |   |   |   |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance   | CAS              | Exempt | Weight  | Unit of Measure |
|----------------------|--------|-----------------|----------|---|------------------|--------|---------|-----------------|
| Die                  | 3.28   | mg              | Supplier | Silicon (Si)  | 7440-21-3        |        | 3.28    | mg              |
| Die Attach           | 0.6    | mg              | Supplier | Isobornyl Methacrylate  | 7534-94-3        |        | 0.036   | mg              |
|                      |        |                 | Supplier | Silver (Ag)   | 7440-22-4        |        | 0.489   | mg              |
|                      |        |                 | Supplier | Isobornyl Acrylate  | 5888-33-5        |        | 0.036   | mg              |
|                      |        |                 | Supplier | Misc.   | Proprietary Data |        | 0.003   | mg              |
|                      |        |                 | Supplier | Tricyclo[5.2.1.02,6]decanedimethanol<br>Diacrylate (C18H24O4) | 42594-17-2       |        | 0.036   | mg              |
| Lead Frame           | 26.96  | mg              | Supplier | Silver (Ag)   | 7440-22-4        |        | 0.5392  | mg              |
|                      |        |                 | Supplier | Tin (Sn)  | 7440-31-5        |        | 0.0674  | mg              |
|                      |        |                 | Supplier | Zinc (Zn)   | 7440-66-6        |        | 0.0593  | mg              |
|                      |        |                 | Supplier | Chromium (Cr)   | 7440-47-3        |        | 0.0674  | mg              |
|                      |        |                 | Supplier | Copper (Cu)   | 7440-50-8        |        | 26.2267 | mg              |
| Mold Compound-Black  | 22.31  | mg              |          | Epoxy resin   | proprietary data |        | 1.0486  | mg              |
|                      |        |                 | Supplier | Silica Amorphous (SiO2)                                       | 7631-86-9        |        | 2.231   | mg              |
|                      |        |                 | Supplier | Carbon Black (C)  | 1333-86-4        |        | 0.0223  | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)   | 60676-86-0       |        | 17.9595 | mg              |
|                      |        |                 | Supplier | Phenolic Resin (Novolac)                                      | 9003-35-4        |        | 1.0486  | mg              |
| Plating              | 2.2    | mg              | Supplier | Tin (Sn)  | 7440-31-5        |        | 2.2     | mg              |
| Wire Bond            | 0.12   | mg              | Supplier | Palladium (Pd)  | 7440-05-3        |        | 0.0012  | mg              |
|                      |        |                 | Supplier | Copper (Cu)   | 7440-50-8        |        | 0.1188  | mg              |